

# **KBJ4005 THRU KBJ410**

- · Glass passivated chip junction
- · Reliable low cost construction utilizing molded plastic technique
- · Ideal for printed circuit board
- · Low forward voltage drop
- · Low reverse leakage current
- · High surge current capability

### MECHANICAL DATA

Case: Molded plastic, KBJ4

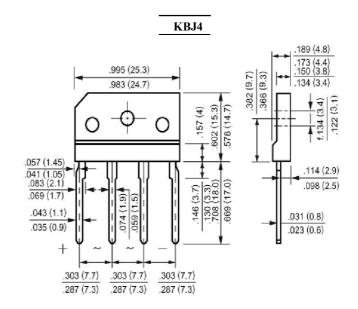
Epoxy: UL 94V-0 rate flame retardant

Terminals: Pure tin plated, lead free, Leads solderable

per MIL-STD-202, method 208 guaranteed

Mounting position: As Marking

Wei ht: 4.21 ram



Dimensions in inches and (millimeters)

### Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

	Symbols	KBJ4005	KBJ401	KBJ402	KBJ404	KBJ406	KBJ408	KBJ410	Units
Maximum Recurrent Peak Reverse Voltage	Vrrm	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current at T <sub>C</sub> =115℃	I(AV)	4.0							Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	Ifsm	120							Amp
Maximum Forward Voltage at 2.0A DC and 25℃	VF	1.0							Volts
Maximum Reverse Current at TA=25℃ at Rated DC Blocking Voltage TA=100℃	IR	5.0 500							uAmp
Typical Junction Capacitance (Note 1)	CJ	40							pF
Typical Thermal Resistance (Note 2)	Rөлс	5.5							℃/W
Operating and Storage Temperature Range	TJ, Tstg	-55 to +150							ပ္

#### NOTES:

- 1- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.
- 2- Thermal Resistance from Junction to Case with Device Mounted on 75mm x 75mm x 1.6mm Cu Plate Heatsink.



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FIG.1- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT PER BRIDGE ELEMENT PEAK FORWARD SURGE CURRENT. (A) 8.3ms Single Half Sine Wave JEDEC METHOD NUMBER OF CYCLES AT 60Hz

